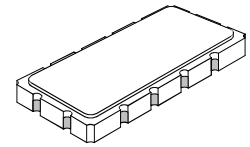





PX1002

**86.85 MHz
SAW Filter**



SM13365-12

- **Designed for TDMA IS-54 Receiver IF Applications**
- **Low Insertion Loss**
- **Excellent Selectivity**
- **Hermetic 13.3 X 6.5 mm Surface-Mount Case**
- **Unbalanced Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)** 

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max Soldering Profile	260°C for 30 s	

Electrical Characteristics


Characteristic	Sym	Notes	Min	Typ	Max	Units	
Nominal Center Frequency	f_c	1	86.850			MHz	
Passband Insertion Loss at f_c 3 dB Passband Amplitude Ripple over $f_c \pm 15$ kHz Group Delay Variation over $f_c \pm 10$ kHz	IL	1, 2		3	4.0	dB	
	BW_3		± 12	± 25		kHz	
					1.0		dB _{P-P}
	GDV				6.0		μ s _{P-P}
Third-Order Intermod. for -20 dBm tones at $f_c \pm 60$ & 120 kHz					-95	dBm	
Rejection $f_c \pm 60$ kHz $f_c - 880$ kHz to $f_c - 940$ kHz Ultimate		1, 2, 3	11	16		dB	
			65				
				65			
Operating Temperature Range	T_A	1	-20		+70	°C	

Impedance Matching to 50 Ω unbalanced	External L-C
Case Style	SM13365-12 13.3 X 6.5 mm Nominal Footprint
Lid Symbolization (YY=year, WW=week) See note 4	RFM PX1002 YYWW

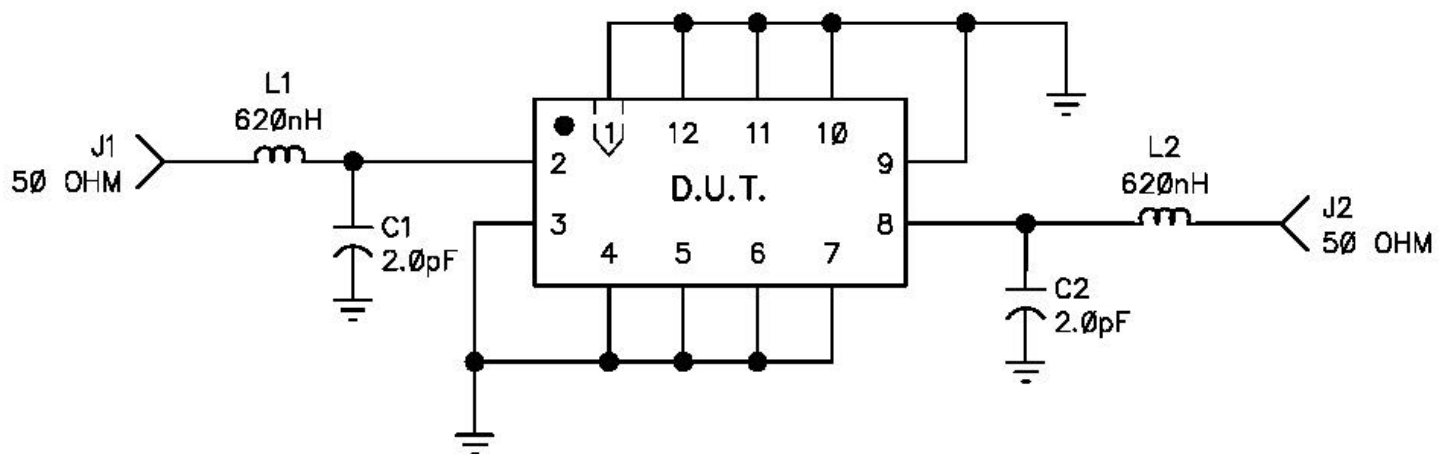
Electrical Connections

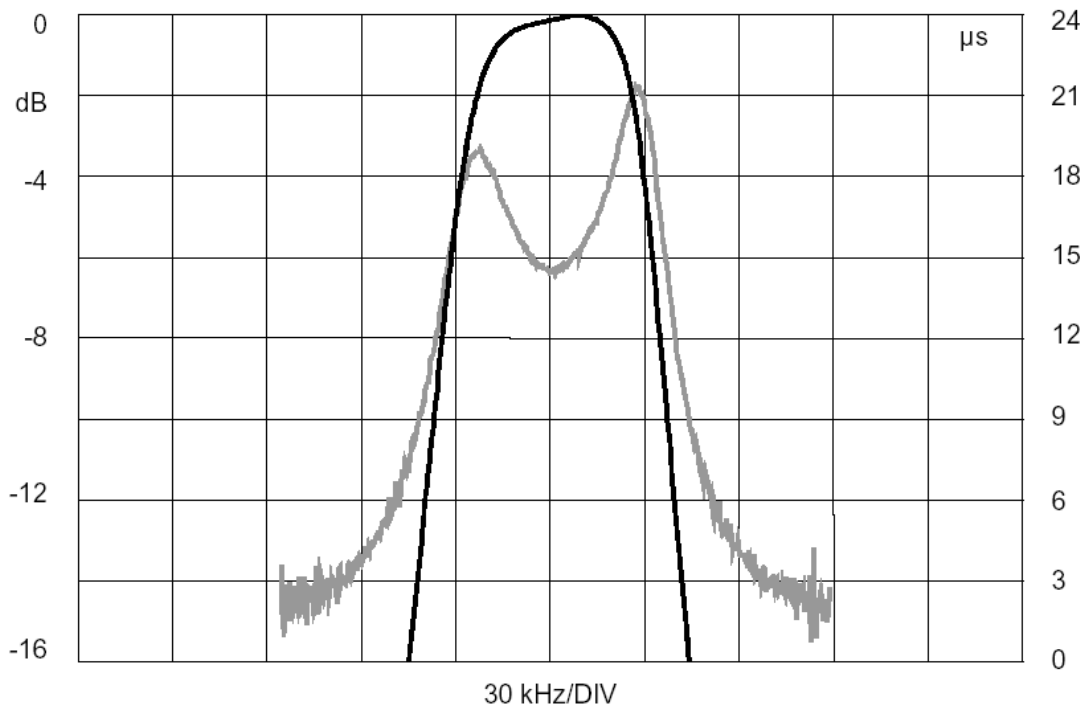
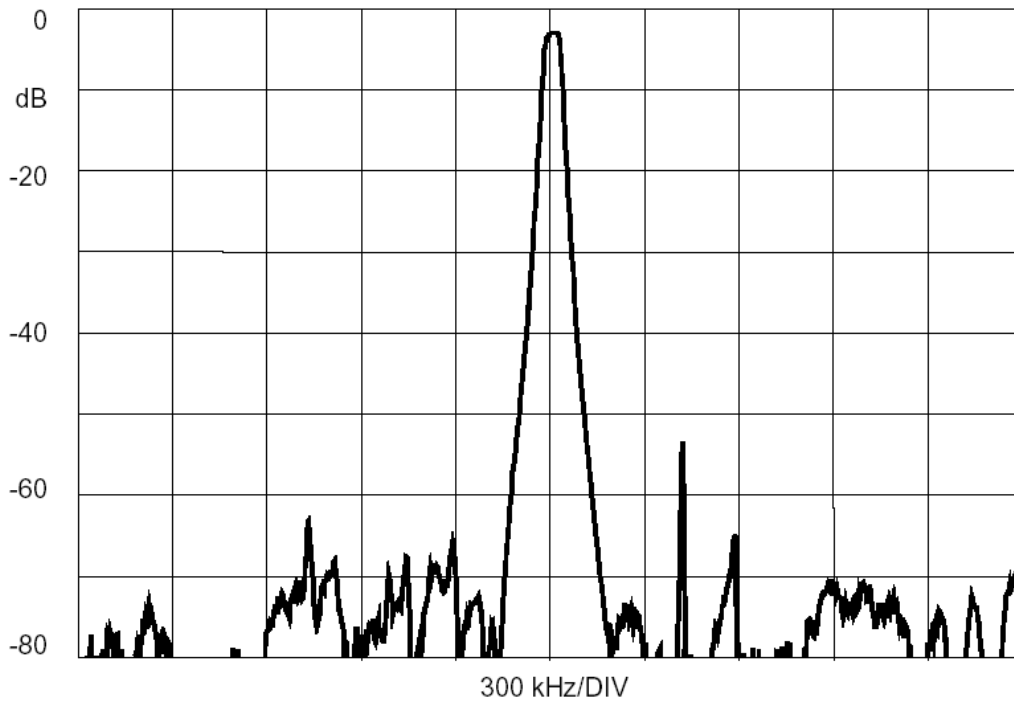
Connection	Terminals
Port 1 Hot	2
Port 1 Gnd Return	3
Port 2 Hot	8
Port 2 Gnd Return	9
Case Ground	All Others

Notes:

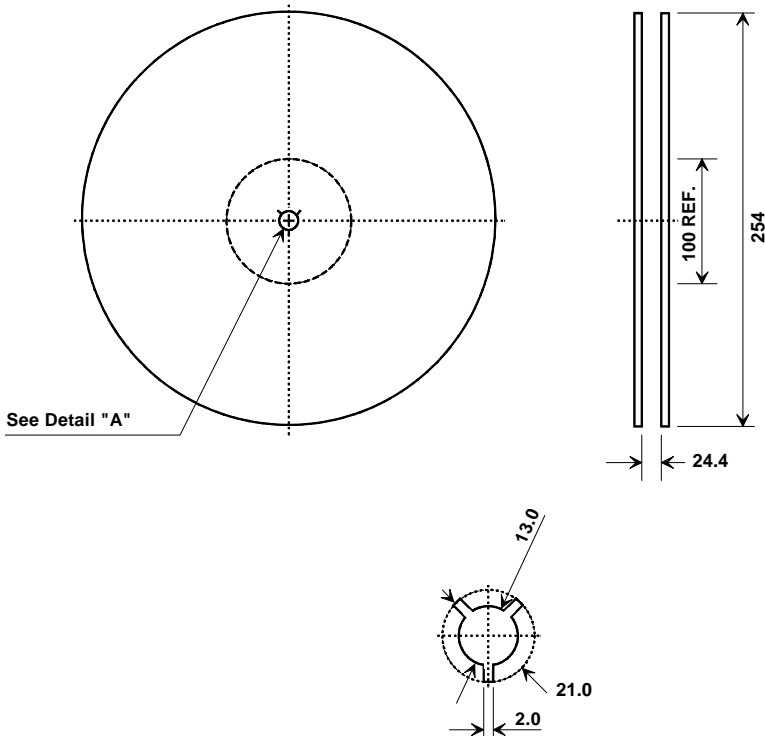
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.
9. ©Copyright 1999, RF Monolithics Inc.
10. Electrostatic Sensitive Device. Observe precautions for handling 

SCHEMATIC, PX1002 (DEMO)





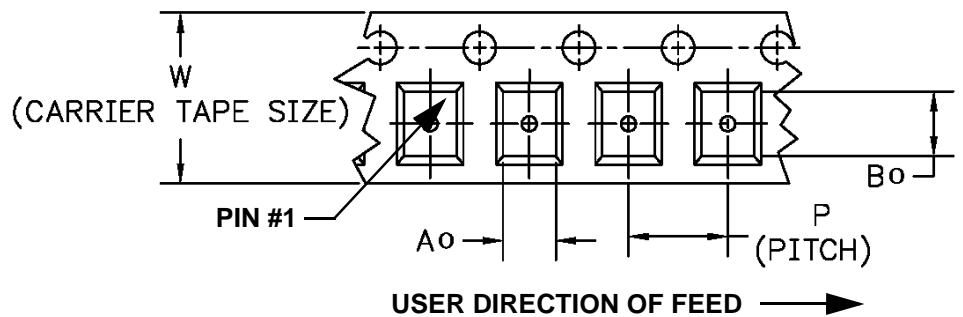
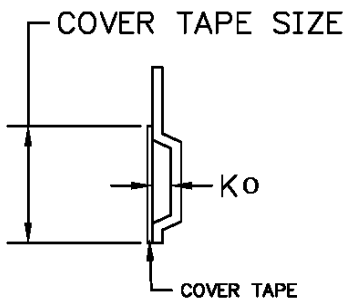
Tape and Reel Specifications



Quantity Per Reel	
100 Min	
1000 Max	

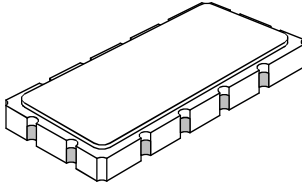
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	7.0 mm
Bo	13.8 mm
Ko	2.0 mm
Pitch	12.0 mm
W	24.0 mm



SM13365-12 Case

12-Terminal Ceramic Surface-Mount Case
13.3 x 6.5 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	13.08	13.31	13.60	0.515	0.524	0.535
B	6.27	6.50	6.80	0.247	0.256	0.268
C		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

Materials	
Solder Pad Termination	Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μinches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

